

REMARKS

Claims 1-22 are pending in the present application. Replacement claims 1, 5-7, and 9-13 are presented herewith. Also, claims 14-22 are presented herewith.

Priority Under 35 U.S.C. 119

Applicant notes the Examiner's acknowledgment of the Claim for Priority under 35 U.S.C. 119 and receipt of the certified copy of the Priority Document.

Drawings

The drawings have been objected to as failing to comply with 37 C.F.R. 1.84(p)(5), because they do not include the reference numerals listed in the second paragraph on page 2 of the application. Responsive to this objection, page 6 has been amended to provide correct reference numerals. Accordingly, the Examiner is respectfully requested to withdraw this particular objection to the drawings.

The drawings have been further objected to as failing to comply with 37 C.F.R. 1.84(p)(5), because they include reference numerals not mentioned in the description. However, as noted above, the specification has been amended on page 6 to correctly describe the reference numerals in the drawings. The Examiner is therefore respectfully requested to withdraw this particular objection to the drawings.

Specification

The specification has been amended on page 3 in view of the objection to the disclosure. The Examiner is therefore respectfully requested to withdraw this corresponding objection.

Claim Objections

Claims 5, 6, 9 and 13 have been objected to in view of the informalities listed on page 3 of the Office Action. The claims have been amended responsive to the Examiner's comments. The Examiner is therefore respectfully requested to withdraw the objection.

Claim Rejections-35 U.S.C. 112

Claims 5 and 6-13 have been rejected under 35 U.S.C. 112, second paragraph, as being indefinite. The claims have been amended responsive to the Examiner's comments to improve form and to be in better compliance with 35 U.S.C. 112, second paragraph. The Examiner is therefore respectfully requested to withdraw this rejection.

Claim Rejections-35 U.S.C. 102

Claims 1-13 have been rejected under 35 U.S.C. 102(b) as being anticipated by the Yoo et al. reference (U.S. Patent No. 5,661,338). This rejection, insofar as it may pertain to the presently pending claims, is traversed for the following reasons.

The semiconductor device of claim 1 features in combination that "a part of said die pad supporter is located between a pair of said inner leads and extends along the pair of said inner leads". Applicant respectfully submits that the Yoo et al. reference as relied upon by the Examiner does not disclose these features.

The Examiner has apparently characterized tie bars T₁-T₄ in Fig. 2 of the Yoo et al. reference as die pad supporters. However, tie bars T₁-T₄ are not located between a pair of inner leads 8 in Fig. 2 of the Yoo et al. reference, and do not extend along a pair of inner leads. Accordingly, Applicant respectfully submits that the semiconductor device of claim 1 distinguishes over the Yoo et al. reference as relied upon by the Examiner, and that this rejection, insofar as it may pertain to claims 1-4, is improper for at least these reasons.

The semiconductor device of claim 5 features in combination that "said die pad supporter has a first portion, a pair of second portions, and a pair of third portions, wherein said first portion is disposed between a pair of said inner leads and extends along the pair of said inner leads...". As emphasized previously, tie bars T₁-T₄ in Fig. 2 of the Yoo et al. reference are not disposed between pairs of inner leads 8, and do not extend along pairs of inner leads 8. Accordingly, Applicant respectfully submits that the semiconductor device of claim 5 distinguishes over the Yoo et al. reference as relied upon by the Examiner, and that this rejection, insofar as it may pertain to claim 5, is improper for at least these reasons.

The semiconductor device of claim 6 features in combination that "said die pads supporter includes a frame portion which has a rectangular shape, a first portion connected between a side portion of said frame portion and the die pad, and a second portion which extends from a corner portion of said frame portion to between a pair of said inner leads, and wherein said frame portion and the first portion are disposed between the inner leads and the die pad". Applicant respectfully submits that the Yoo et al. reference as relied upon by the Examiner does not disclose these features.

The Examiner has alleged that the Yoo et al. reference also discloses a rectangular frame included in a frame portion with multiple portions. However, the Examiner has failed to particularly identify on the record how Fig. 2, or any of the other figures of the Yoo et al. reference, may be interpreted as including these features. Particularly, the Examiner has failed to establish how the Yoo et al. reference may be interpreted as including a first portion connected between a side portion of a frame portion and a side pad, and/or a second portion which extends from a corner portion of a frame portion to between a pair of inner leads. Applicant respectfully submits that the Yoo et al. reference as relied upon by the Examiner does not disclose these features. Accordingly, Applicant further respectfully submits that the semiconductor device of claim 6 distinguishes over the Yoo et al. reference as relied upon by the Examiner, and that this rejection, insofar as it may pertain to claims 6-9, is improper for at least these reasons. **If this rejection is to be maintained, the Examiner is respectfully requested to establish on the record how the Yoo et al. reference may be**

specifically interpreted to include the features of claim 6.

Applicant also respectfully submits that the semiconductor device of claim 10 distinguishes over the Yoo et al. reference as relied upon by the Examiner for at least somewhat similar reasons as set forth above with respect to claim 6. Particularly, the Examiner has failed to establish on the record how the Yoo et al. reference may be interpreted as including a frame portion "which substantially surrounds the die pad and is disposed between said inner leads and said die pad", first die pad supporters "each of which supports the frame portion from four directions", and a second die pad supporter "which connects the frame portion and said die pad". The Examiner has merely asserted that the Yoo et al. reference discloses a rectangular frame and portions extending in four directions, but has failed to particularly identify the respective elements in the figures of the Yoo et al. reference that have been interpreted as corresponding to these features. Applicant therefore respectfully submits that this rejection is improper for at least these reasons. Accordingly, Applicant respectfully submits that the semiconductor device of claim 10 distinguishes over the Yoo et al. reference as relied upon by the Examiner, and that this rejection, insofar as it may pertain to claims 10-13, is improper for at least these reasons.

Claims 14-21

Applicant respectfully submits that claims 14-21, as respectively dependent upon independent claims 1, 5, 6 and 10, distinguish over and would not have been obvious in

view of the prior art as relied upon by the Examiner, for at least the reasons as set forth above and by further reason of the features therein.

Conclusion

The Examiner is respectfully requested to reconsider and withdraw the above noted rejection and objections, and to pass the claims of the present application to issue, for at least the above reasons.

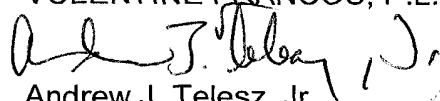
In the event that there are any outstanding matters remaining in the present application, the Examiner is invited to contact Andrew J. Telesz, Jr. (Reg. No. 33,581) at (703) 715-0870 in the Washington, D.C. area, to discuss these matters.

Pursuant to the provisions of 37 C.F.R. 1.17 and 1.136(a), the Applicant hereby petitions for an extension of one (1) month to October 27, 2002, for the period in which to file a response to the outstanding Office Action. The required fee of \$110.00 is attached hereto.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 50-0238 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17; particularly, extension of time fees.

Respectfully submitted,

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Enclosures: Version with Marked-Up Changes